

CC3200-LAUNCHL : Rev 3.2

Bom Revision : A

Date : 20-Jun-2014

Item Numl	Quantity	Part Reference	Value	Mfr_Name	Mfr_Part_Number	Description
1	2	C1 C4	10uF	Murata	GRM21BR61A106KE19L	CAP CER 10UF 10V 10% X5R 0805
2	25	C2 C3 C7 C8 C9 C11 C14 C15	0.1uF	Taiyo Yuden	LMK105BJ104KV-F	CAP CER 0.1UF 10V 10% X5R 0402
3	1	C5	33000 pF	Samsung	CL05B333K05NFNC	CAP 33000PF 16V CERAMIC X7R 0402
4	1	C6	15pF	Murata Electronics North America	GRM1555C1H150JA01D	CAP CER 15PF 50V 5% NPO 0402
5	2	C10 C12	27pF	Murata Electronics North America	GRM1555C1E270JA01D	CAP CER 27PF 25V 5% NPO 0402
6	5	C13 C16 C27 C32 C43	10uF	Murata Electronics North America	GRM188R60J106ME47D	CAP CER 10UF 6.3V 20% X5R 0603
7	2	C23 C24	100uF	TDK Corporation	C3216X5R0J107M160AB	CAP CER 100UF 6.3V 20% X5R 1206
8	2	C25 C26	10pF	Murata Electronics North America	GRM1555C1H100FA01D	CAP CER 10PF 50V 1% NPO 0402
9	3	C33 C38 C40	4.7uF	Samsung Electro-Mechanics America, Inc	CL05A475MQ5NRNC	CAP CER 4.7UF 6.3V 20% X5R 0402
10	2	C34 C36	22uF	Taiyo Yuden	AMK107BBJ226MAHT	CAP CER 22UF 4V 20% X5R 0603
11	1	C46	0.033uF	Murata Electronics North America	GRM155R61A333KA01D	CAP CER 0.033UF 10V 10% X5R 0402
12	2	C47 C48	6.2pF	Murata Electronics North America	GRM1555C1H6R2BA01D	CAP CER 6.2PF 50V NPO 0402
13	1	C49	10pF	AVX Corporation	04025U100CAT2A	CAP CER 10PF 50V NPO 0402
14	1	C50	1.0pF	Murata Electronics North America	GJM1555C1H1R0BB01D	CAP CER 1PF 50V NPO 0402
15	2	D1 D6	LED	OSRAM Opto Semiconductors Inc	LY Q976-P1S2-36	LED CHIPLED 587NM YLW 0603 SMD
16	2	D2 D5	LED	OSRAM Opto Semiconductors Inc	LG Q971-KN-1	LED CHIPLED 570NM GREEN 0603 SMD
17	1	D3	CD0603-B00340	Bourns Inc	CD0603-B00340	DIODE SCHOTTKY 40V 0.03A 0603
18	2	D4 D7	LED	OSRAM Opto Semiconductors Inc	LS Q976-NR-1	LED CHIPLED 633NM RED 0603 SMD
19	1	E1	2.45GHz Ant	Taiyo Yuden	AH316M245001-T	ANT BLUETOOTH W-LAN ZIGBEE WIMAX
20	1	FL1	2.4GHz Filter	TDK-Epcos	DEA202450BT-1294C1	FILTER BANDPASS 2.45GHZ WLAN SMD
21	1	J1	CONN_MICRO_USB	FCI	10118194-0001LF	CONN USB MICRO B RECPST SMT R/A
22	13	J2 J3 J4 J8 J9 J10 J11 J12 J13	HEADER_2	TE Connectivity	5-146285-2	CONN HEADR BRKWAY .100 2POS STR
23	1	J5	HEADER_5	Molex/GC/Waldom Inc.	22-28-4051	CONN HEADER VERT 5 POS .100 TIN
24	4	J6 J7 J19 J20	HEADER_3	TE Connectivity	5-146282-3	CONN HDR BRKWAY .100 3POS VERT
25	1	J18	CONN_U.FL	Emerson Network Power Connectivity Johnson	128-0711-201	CONN UMC RCPT STR 50 OHM SMD
26	2	J22 J23	CONN_RCPT_10x2	Samtec	SSQ-110-03-G-D	CONN RCPT .100" 20POS DUAL GOLD
27	1	J24	RF SWITCH	Murata	MM8030-2610RJ3	CONN SWG JACK STR 50 OHM SMD
28	2	L1 L2	FB	Samsung	CIM10U800NC	FERRITE CHIP 80 OHM 600MA 0603 SMD
29	1	L3	10uH	Taiyo Yuden	CB2518T100K	INDUCTOR POWER 10UH 1007
30	0	L4	DNP	DNP	DNP	DNP
31	2	L5 L7	2.2uH	Murata Electronics North America	LQM2HPN2R2MG0L	INDUCTOR 2.2UH 20% 1300MA 1008
32	1	L6	1uH	Murata	LQM2HPN1R0MJ0L	INDUCTOR POWER 1.0UH 1007
33	0	L8	DNP	DNP	DNP	DNP
34	1	L9	3.6nH	Murata Electronics North America	LQP15MN3N6B02D	INDUCTOR 3.6NH 0.1NH 0402
35	4	Q1 Q3 Q4 Q5	BSS138LT3G	On Semi	BSS138LT3G	MOSFET N-CH 50V 200MA SOT-23
36	1	Q2	SI2323DS-T1-GE3	Vishay	SI2323DS-T1-GE3	MOSFET P-CH 20V 3.7A SOT23-3
37	1	R1	100R	Panasonic - ECG	ERJ-2GEJ101X	RES 100 OHM 1/10W 5% 0402 SMD
38	2	R2 R64	0.1 R	Panasonic	ERJ-S6SFR10V	RES 0.1 OHM 1/4W 1% 0805 SMD
39	6	R3 R4 R20 R125 R126 R127	270	Panasonic Electronic Components	ERJ-3GEYJ271V	RES 270 OHM 1/10W 5% 0603 SMD
40	6	R5 R58 R59 R118 R120 R122	100k	Yageo	RC0402JR-07100KL	RES 100K OHM 1/16W 5% 0402 SMD
41	19	R6 R7 R11 R13 R14 R16 R22	10k	Yageo	RC0402JR-0710KL	RES 10K OHM 1/16W 5% 0402 SMD
42	2	R8 R9	28	Yageo	RC0402FR-0728RL	RES 28.0 OHM 1/16W 1% 0402 SMD
43	1	R10	1.5k	Yageo	RC0402FR-071K5L	RES 1.50K OHM 1/16W 1% 0402 SMD
44	1	R12	2.2K	Panasonic	ERJ-2GEJ222X	RES 2.2K OHM 1/10W 5% 0402 SMD
45	15	R15 R19 R25 R26 R28 R29 R33	33	Yageo	RC0402FR-0733RL	RES 33.0 OHM 1/16W 1% 0402 SMD
46	1	R17	51K	Samsung	RC1005F513CS	RES 51K OHM 1/16W 1% 0402
47	1	R18	30.1K	Yageo	RC0402FR-0730K1L	RES 30.1K OHM 1/16W 1% 0402 SMD

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48	1	R21	470	Yageo	RC0402FR-07470RL	RES 470 OHM 1/16W 1% 0402 SMD
49	44	R23 R27 R32 R38 R39 R42 R	0 R	Panasonic Electronic Components	ERJ-2GE0R00X	RES 0.0 OHM 1/10W JUMP 0402 SMD
50	13	R24 R31 R63 R71 R74 R76 R	DNP	DNP	DNP	DO NOT MOUNT
51	1	R37	DNP	DNP	DNP	DO NOT MOUNT
52	2	R47 R54	3.3K	Panasonic - ECG	ERJ-2GEJ332X	RES 3.3K OHM 1/10W 5% 0402 SMD
53	3	R57 R116 R124	1k	Yageo	RC0402JR-071KL	RES 1.0K OHM 1/16W 5% 0402 SMD
54	0	R62	DNP	DNP	DNP	DNP
55	0	R79 R81 R86 R88 R90	DNP	DNP	DNP	DNP
56	1	R100	3.3M	Yageo	RC0402FR-073M3L	RES 3.30M OHM 1/16W 1% 0402 SMD
57	0	R112	DNP	DNP	DNP	DNP
58	3	SW1 SW2 SW3	SW TACT	Panasonic	EVQ-11A04M	SWITCH TACTILE SPST-NO 0.02A 15V
59	1	TP1	TP_1206	TE Connectivity	1625854-4	1206 PROBE PAD
60	1	U1	TPD2EUSB30	TI	TPD2EUSB30DRTR	IC ESD SOLUTION 2CH SOT3
61	1	U2	93LC46B-I/MS	Microchip	93LC46B-I/MS	IC SRL EE 1K 64X16 2.5V 8MSOP
62	1	U3	TPS79601	TEXAS INSTRUMENTS INC	TPS79601DCQR	IC,VREG,LDO,1.2V-5.5V,2.7V-5.5V,-,6PIN,SOT-223
63	1	U5	FT2232D	FUTURE TECHNOLOGY DEVICES INTERNATIONAL LTD	FT2232D	IC, USB UART/FIFO, MPSSE, 12/48MHz, 48-PIN, LQFP
64	1	U6	TMP006	Texas Instruments	TMP006AIYZFR	IC SENSOR THERMOPILE 8DSBGA
65	1	U8	TPS61097-33DBVR	TEXAS INSTRUMENTS INC	TPS61097-33DBVR	IC REG BST SYNC 3.3V .1A SOT23-5
66	1	U10	BMA222	Bosch	BMA222E	3-AXIS ACCELEROMETER DIGITAL SMD
67	2	U11 U12	SN74LVC1T45D	TEXAS INSTRUMENTS INC	SN74LVC1T45DCKR	IC, BUS XCVR, 1-BIT, NON INVERTING, 3-STATE, 6-PIN, SOT-23
68	1	U13	CC3200	Texas Instruments	XCC3200HZ	ARM M4 MCU with 802.11bg WIFI
69	0	U14	DNP	DNP	DNP	DNP
70	1	U15	8M (1M x 8)	Micron Technology Inc	M25PX80-VMN6TP	IC FLASH 8MBIT 75MHZ 8SO
71	2	U4 U9	SN74LVC125APWR	TEXAS INSTRUMENTS INC	SN74LVC125APWR	IC BUS BUFF TRI-ST QD 14TSSOP
72	1	U7	SN74LVC126APWR	TEXAS INSTRUMENTS INC	SN74LVC126APWR	IC BUS BUFF TRI-ST QD 14TSSOP
73	1	Y1	CRYSTAL	Epson	CA-301 6.0000M-C-PBFFREE	CRYSTAL 6MHZ 18PF THRU
74	1	Y2	Crystal	Abracon Corporation	ABS07-32.768KHZ-T	CRYSTAL 32.768KHZ 12.5PF SMD
75	1	Y3	Crystal	Epson	Q24FA20H00396	CRYSTAL 40MHZ 8PF SMD

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